AMENDMENT

To the Claims:

1. (currently amended) A mechanism for compressing chips, comprising:

a loading component;

a head component disposed under the loading component, wherein the head component has a heating plate therein, and a gap is existed between the loading component and the head component, and wherein the head component has a groove and the bottom of the loading component is partially inset into the groove, the head component comprising:

a first gasket having a contact part with the gimbal;

a ring piece fixed on the first gasket, wherein the ring piece has a hollow portion such that the groove is existed between the ring piece and the first gasket; and

a gimbal disposed between the loading component and the head component to support the gap therebetween.

2-3. (canceled)

4. (original) The mechanism for compressing chips of claim 3, wherein the upper surface of the first gasket has a first notch, where the gimbal is disposed.

5. (previously presented) The mechanism for compressing chips of claim 3, wherein the heating plate is fixed under the bottom surface of the first gasket.

6. (previously presented) The mechanism for compressing chips of claim 5, wherein the head component further comprises a second gasket fixed below the heating plate, such that the heating plate is placed between the first gasket and the second gasket.

7. (original) The mechanism for compressing chips of claim 6, wherein the head component further comprises at least one fixing piece joining the ring piece, the first gasket, the heating plate and the second gasket.

8. (original) The mechanism for compressing chips of claim 7, wherein the fixing piece comprises a screw.

9. (original) The mechanism for compressing chips of claim 1, wherein the bottom surface of the loading component has a second notch, where the gimbal is disposed.

Claims 10-19 (canceled)